SD-Wi-Fi-UART-BT-FP91-IW416 Firmware Release Notes for FreeRTOS



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Revision History

Table 1: Document revision history

Revision	Date	Change details
Rev.1	05-Jan-2021	Initial release
Rev.2	19-Mar-2021	Section 1 and Section 2 Updated
Rev.3	27-Aug-2021	Section 1 Updated
		Section 5 Updated
Rev.4	05-Jan-2022	Section 1 and Section 2 Updated
		Section 5 and Section 7 Updated
		Section 8 Updated
Rev. 5	15-Mar-2022	Section 1 "Package Information": updated sdk version
		Section 5.1 "Throughput Test Setup": updated setup details
		Section 5.2 "STA Throughput": updated TP numbers, added new case for
		2.4GHz 40MHz
		Section 5.3 "AP Throughput": updated TP numbers, added new case for
		2.4GHz 40MHz
		Section 7 "Bug Fixes/Feature Enhancements": updated

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1 Package Information

- SDK version: 2.11.1
- Wi-Fi and Bluetooth/Bluetooth LE Firmware version: 16.91.21.p11.3

Please refer to the Software feature list in the document SD-Wi-Fi-UART-BT-IW416-Wi-Fi-and-Bluetooth-Software-Features-for-FreeRTOS.

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2 Firmware Version Information

- Wireless SoC : IW416
- Wi-Fi and Bluetooth/Bluetooth LE Firmware version: 16.91.21.p11.3
 - 16 Major revision
 - 91 Feature pack
 - 21 Release version
 - p11.3 Patch number

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3 Host Platform

- All i.MX RT Platform running FreeRTOS
- Interface used
 - o Wi-Fi over SDIO (SDIO 2.0 support, SDIO clock frequency: 50 MHz)
 - o Bluetooth/Bluetooth LE over UART

Test Tools

• iperf (version 2.0.5)

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4 Wi-Fi Pre-Certification and Bluetooth Qualification

The Wi-Fi pre-certification obtained with the following combinations.

- 4.1 Wi-Fi Pre-Certification
- STA | 802.11n
- STA | PMF
- 4.2 Bluetooth Controller Qualification
- QDID: https://launchstudio.bluetooth.com/ListingDetails/108035

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5 Wi-Fi Throughput

5.1 Throughput Test Setup

• Environment: Shield Room - Over the Air

• Access Point: linksys WRT1100AC and TP-Link Archer 6000

DUT: IW416 Azurewave (Module: AW-AM457MA-uSD) with EVK-MIMXRT1060 platform

• Client: Apple Macbook Air

• Channel: 6 | 36

Wi-Fi application: wifi_cli

• Compiler used to build application: armgcc

• Compiler Version: gcc-arm-none-eabi-9-2020-q2-update

• iPerf Commands used in test:

TCP TX	TCP RX	UDP TX	UDP RX
iperf -c <remote_ip> -t</remote_ip>	iperf -s	iperf -c <remote_ip> -t 60 -u -B <local_ip></local_ip></remote_ip>	iperf -s -u -B
60		-b 120	<local_ip></local_ip>
		NOTE: Defaults data rate is 100mbps	

Refer to **Section-3.1.1** in *UM11442-NXP Wi-Fi* and *Bluetooth Demo Applications User Guide for i.MX RT Platforms* to read more about the throughput test setup and topology.

5.2 STA Throughput

External AP: linksys WRT1100AC (Open/WPA2) and TP-Link Archer 6000 (WPA3-SAE)

STA Mode Throughput - BGN Mode 2.4 GHz Band 20 MHz				
Protocol	TCP (N	lbit/s)	UDP (I	Mbit/s)
Direction	Tx	Rx	Tx	Rx
Open Security	29.7	31	39.8	55
WPA2-AES	25.2	32	43.6	50
WPA3-SAE	32.1	37	43.2	55

	STA Mode Throughput - BGN Mode 2.4 GHz Band 40 MHz				
Protocol	TCP (M	lbit/s)	UDP (I	Mbit/s)	
Direction	Tx	Rx	Tx	Rx	
Open Security	47.4	56	69.1	109	
WPA2-AES	42.7	52	56.6	100	
WPA3-SAE	43.7	52	64.7	98	

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STA Mode Throughput - AN Mode 5 GHz Band 20 MHz						
Protocol	TCP (M	TCP (Mbit/s)		TCP (Mbit/s) UDP (Mbit/s)		Mbit/s)
Direction	Tx	Rx	Tx	Rx		
Open Security	32.8	35	50	59		
WPA2-AES	33.1	35	45	53		
WPA3-SAE	32.8	38	43.7	55		

	STA Mode Throughput - AN Mode 5 GHz Band 40 MHz				
Protocol	TCP (M	lbit/s)	UDP (Mbit/s)	
Direction	Tx	Rx	Tx	Rx	
Open Security	45	50	84.8	110	
WPA2-AES	44.5	47	94.1	107	
WPA3-SAE	34.1	48	94.1	104	

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5.3 Mobile AP Throughput

External client: Apple Macbook Air

Mobile AP Mode Throughput - BGN Mode 2.4 GHz Band 20MHz				
Protocol	TCP (M	lbit/s)	UDP	(Mbit/s)
Direction	Tx	Rx	Tx	Rx
Open Security	22	29	42	60
WPA2-AES	29.9	41	43.3	59
WPA3-SAE	24.8	41	42.3	60

Mobile AP Mode Throughput - BGN Mode 2.4 GHz Band 40MHz				
Protocol	TCP (M	lbit/s)	UDP	(Mbit/s)
Direction	Tx	Rx	Tx	Rx
Open Security	32	53	71.8	81
WPA2-AES	32	53	71.8	81
WPA3-SAE	28	51	73.5	82

	Mobile AP Mode Throughput - AN Mode 5 GHz Band 20 MHz				
Protocol	TCP (M	bit/s)	UDP	(Mbit/s)	
Direction	Tx	Rx	Tx	Rx	
Open Security	26	35	43	64	
WPA2-AES	34.6	46	44.8	64	
WPA3-SAE	27.6	46	44.8	63	

Mobile AP Mode Throughput - AN Mode 5 GHz Band 40 MHz				
Protocol	TCP (N	/lbit/s)	UDP (Mbit/s)	
Direction	Tx	Rx	Tx	Rx
Open Security	25	43	80	99
WPA2-AES	30.3	59	83.2	98
WPA3-SAE	31.3	59	81	99

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6 EU Conformance Tests

- EU Adaptivity test EN 300 328 v2.1.1 (for 2.4 GHz)
- EU Adaptivity test EN 301 893 v2.1.1 (for 5 GHz)

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7 Bug Fixes/Feature Enhancements

Component	Description				
Wi-Fi	 Low RSSI values observed in uAP BGN-20 in all securities, in shielded/noisy environment, connectivity issue observed Added support for IPv6 Added support for HT40 in 2.4GHz AP and STA 				

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8 Known Issues

Component	Description

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9 Notes

• None

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